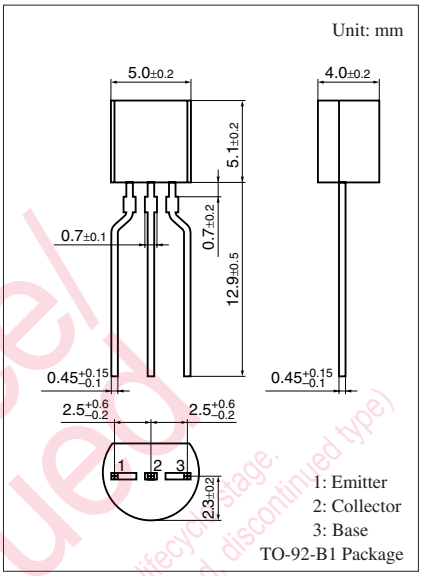
2SC1318A

Silicon NPN epitaxial planar type

For low-frequency driver amplification
Complementary to 2SA0720A



■ Features

- High collector-emitter voltage (Base open) V_{CEO}
- Optimum for the driver stage of a low-frequency and 25 W to 30 W output amplifier

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	80	V
Collector-emitter voltage (Base open)	V_{CEO}	70	V
Emitter-base voltage (Collector open)	V_{EBO}	5	V
Collector current	I_C	0.5	A
Peak collector current	I_{CP}	1	A
Collector power dissipation	P_C	750	mW
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

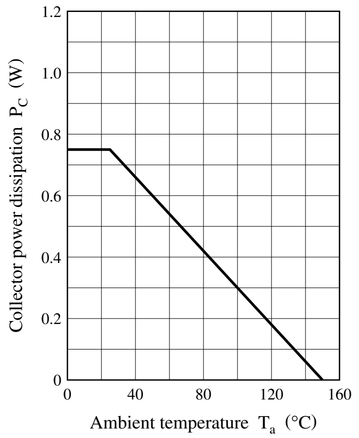
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	I_C = 10 µA, I_E = 0	80			V
Collector-emitter voltage (Base open)	V_{CEO}	I_C = 2 mA, I_B = 0	70			V
Emitter-base voltage (Collector open)	V_{EBO}	I_E = 10 µA, I_C = 0	5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	V_{CB} = 20 V, I_E = 0			0.1	µA
Forward current transfer ratio *1	h_{FE1} *2	V_{CE} = 10 V, I_C = 150 mA	85		340	—
	h_{FE2}	V_{CE} = 10 V, I_C = 500 mA	40			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	I_C = 300 mA, I_B = 30 mA		0.2	0.6	V
Base-emitter saturation voltage	$V_{BE(sat)}$	I_C = 300 mA, I_B = 30 mA		0.85	1.50	V
Transition frequency	f_T	V_{CB} = 10 V, I_E = –50 mA, f = 200 MHz		120		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	V_{CB} = 10 V, I_E = 0, f = 1 MHz		11	20	pF

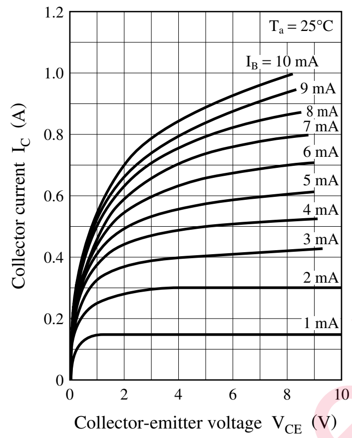
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. ∗1: Pulse measurement
∗2: Rank classification

Rank	Q	R	S
h_{FE1}	85 to 170	120 to 240	170 to 340

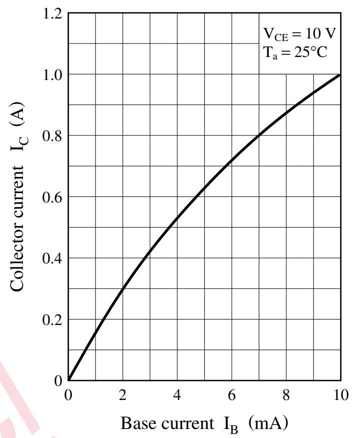
P_C — T_a



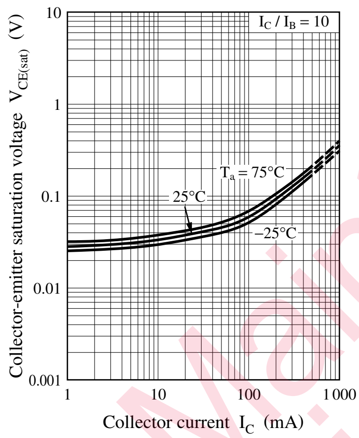
I_C — V_{CE}



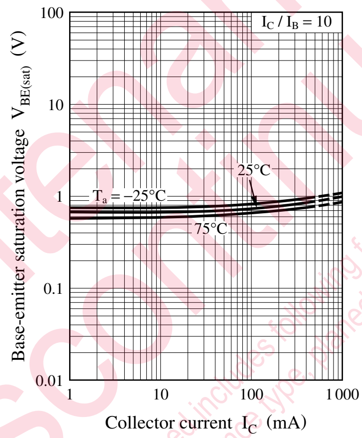
I_C — I_B



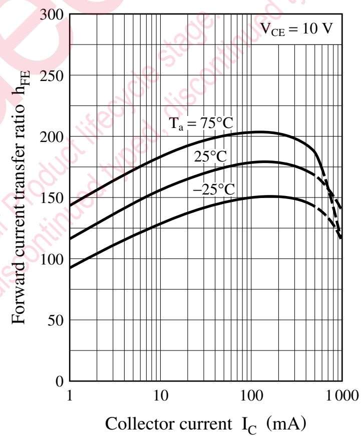
$V_{CE(sat)}$ — I_C



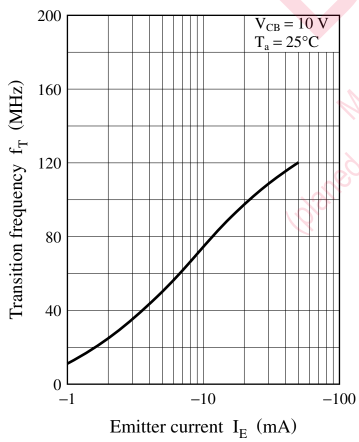
$V_{BE(sat)}$ — I_C



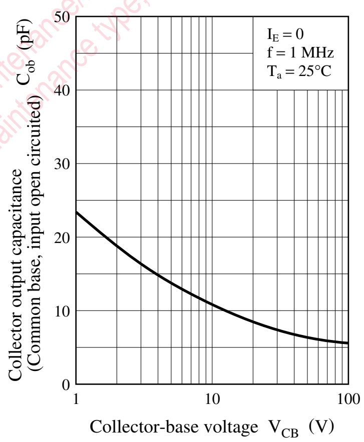
h_{FE} — I_C



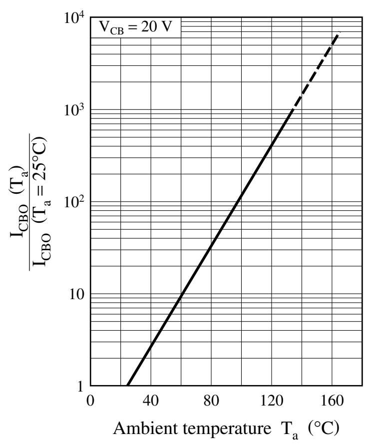
f_T — I_E



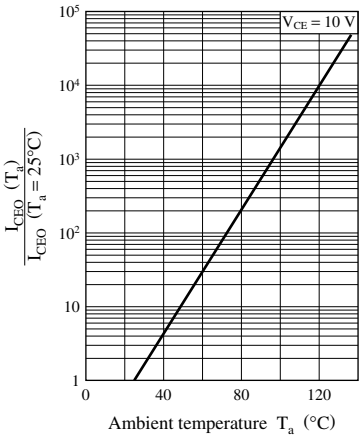
C_{ob} — V_{CB}



I_{CBO} — T_a



I_{CEO} — T_a



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